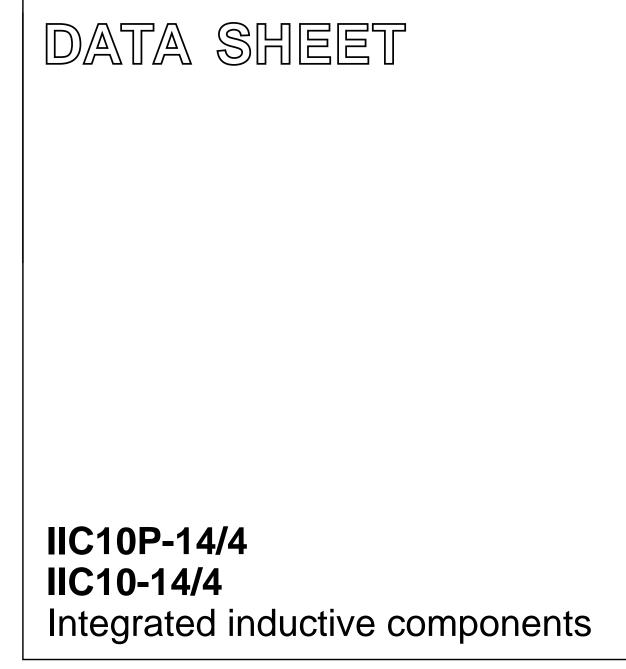
## FERRITE CERAMICS



Product specification File under Ferrite Ceramics, MA01 1999 Dec 23







# IIC10P-14/4

### Effective core parameters

SYMBOL	PARAMETER	VALUE	UNIT
Σ(I/A)	core factor (C1)	2.47	mm <sup>-1</sup>
Ve	effective volume	338	mm <sup>3</sup>
l <sub>e</sub>	effective length	28.9	mm
A <sub>e</sub>	effective area	11.7	mm <sup>2</sup>
m	mass of core half	≈1.85	g

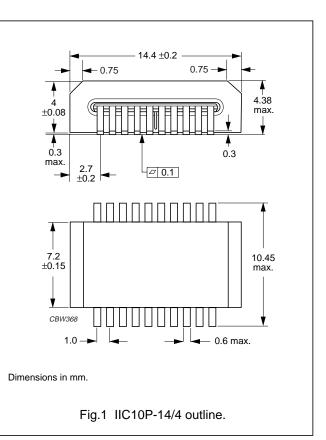
### FEATURES

- Inductive SMD component that looks like a standard IC.
- Windings are completed by PCB tracks.
- Suitable for reflow soldering.
- Partial air gap to resist saturation.
- Number of turns can be adpated by track layout.

## APPLICATIONS

- Power inductor
- Output choke
- EMI choke with bias current.

### IICs with partial air gap for use as power inductors



GRADE	L (μΗ) FOR 10 TURNS NO BIAS CURRENT			L (μH) FOR 10 TURNS WITH A BIAS CURRENT OF 1 A			
GRADE	f = 100 kHz; T = 25 °C	f = 500 kHz; T = 25 °C	f = 1 MHz; T = 25 °C	f = 100 kHz; T = 25 °C	f = 500 kHz; T = 25 °C	f = 1 MHz; T = 25 °C	ITFE NUMBER
3C30	92 ±25%	_	_	≥5	_	_	IIC10P-14/4-3C30
3F4	_	_	45 ±25%	-	_	≥5	IIC10P-14/4-3F4
3F35	-	70 ±25%	_	-	≥5	_	IIC10P-14/4-3F35

#### IICs with partial air gap under power conditions

	CORE LOSS (mW)			
GRADE	f = 100 kHz; Ê = 100 mT; T = 100 °C	f = 500 kHz; Ĝ = 50 mT; T = 100 °C	f = 1 MHz; Ê = 30 mT; T = 100 °C	TYPE NUMBER
3C30	≤30	_	_	IIC10P-14/4-3C30
3F4	_	_	≤70	IIC10P-14/4-3F4
3F35	_	≤40	_	IIC10P-14/4-3F35

## IIC10P-14/4

### IIC10-14/4

### Effective core parameters

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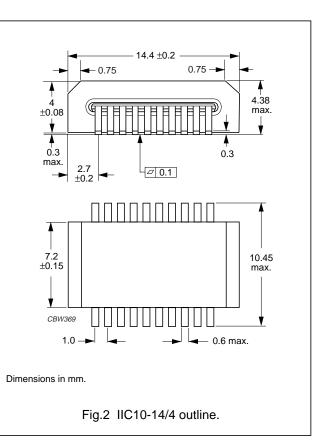
### FEATURES

- Inductive SMD component that looks like a standard IC.
- Windings are completed by PCB tracks.
- Suitable for reflow soldering.
- Several magnetic functions, depending on track layout.

### APPLICATIONS

- Common-mode choke
- Mutli-line choke
- Power transformers
- Signal transformers
- Saturable inductor.

### IICs for use as transformer or common-mode chokes



	A <sub>L</sub> (nH) at		CORE LC			
GRADE	1 = 10  MHz,	f = 500 kHz; T = 25 °C		f = 500 kHz; Ê = 50 mT; T = 100 °C	f = 1 MHz; Ê = 30 mT; T = 100 °C	TYPE NUMBER
3F4	—	_	450 ±25%	_	≤70	IIC10-14/4-3F4
3E6	6000 ±30%	_	_	_	_	IIC10-14/4-3E6
3F35	_	700 ±25%	_	≤40	_	IIC10-14/4-3F35

### IIC for use as a common-mode choke or multi-line choke

GRADE	Z  Ω for 1 turn at f = 100 MHz; T = 25 °C <sup>(1)</sup>	TYPE NUMBER
3S4	≈35	IIC10-14/4-3S4

#### Note

1. Minimum value,  $|Z|_{min}$  is -20%.

### IIC with rectangular hysteresis loop for use in magnetic regulators

	E t produc		
GRADE	f = 100 kHz; H = 800 A/m;         f = 100 kHz; H = 800 A/m;           T = 100 °C; I <sub>reset</sub> = 70 mA; 10 turns         T = 100 °C; I <sub>reset</sub> = 0 mA; 10 turns		TYPE NUMBER
3R1	≥33	≤12	IIC10-14/4-3R1

## IIC10-14/4

## IIC10-14/4

#### **GENERAL DATA**

#### R<sub>dc</sub>

 ${\approx}65~m\Omega$  (25 °C) and  ${\approx}85~m\Omega$  (100 °C) for 10 turns including 20 solder joints (assuming 70  $\mu m$  Cu PCB tracks).

#### Leadframe material

Copper, plated with tin-lead alloy SnPb (85/15).

#### Solderability

Compatible with reflow soldering, "IEC 60068-2-58, part 2, test Ta, method 1".

#### Moulding material

Liquid crystal polymer (LCP), flame retardant in accordance with "UL 94V-0".

#### **Isolation voltage**

 $>\!500$  V (DC) between leads and between leads and ferrite core.

#### **Isolation resistance**

>100 M $\Omega$  between leads.

#### Inter winding capacitance

2 windings of 5 turns: unifilar ≈5 pF bifilar ≈10 pF.

(depending on track layout; see Figs 1 and 2)

#### Leakage inductance

2 windings of 5 turns: unifilar ≈1.8 μH bifilar ≈0.2 μH.

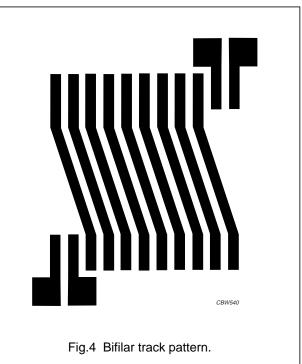
#### Maximum continuous current (DC)

4 A (depending on copper track thickness on PCB).

#### Maximum peak current

10 A.

Remove for use as 5+5 turns



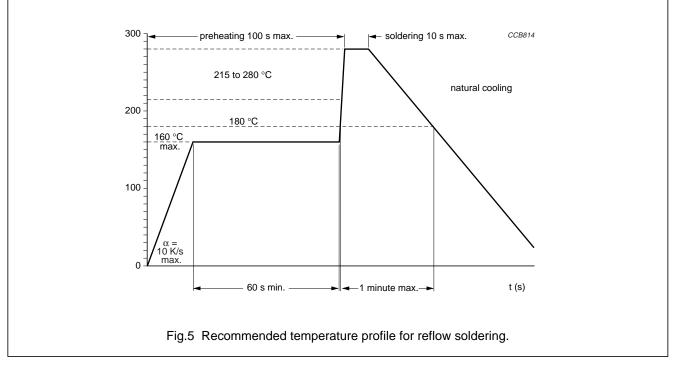
IIC10P-14/4

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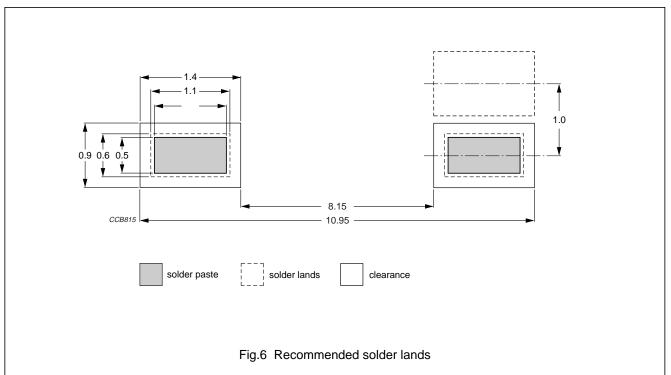
## Integrated inductive components

## MOUNTING

### Soldering information



#### RECOMMENDED SOLDER LANDS



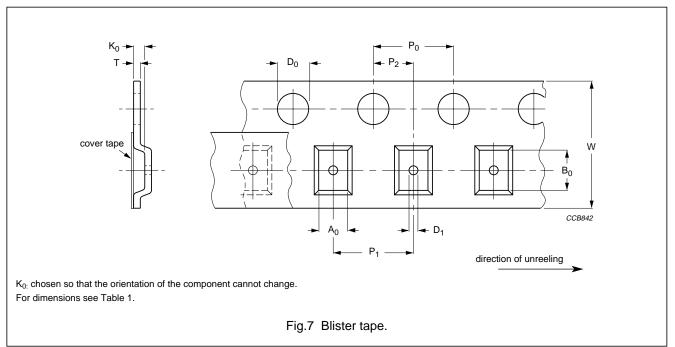
## IIC10P-14/4 IIC10-14/4

### PACKAGING

### Tape and reel specifications

All tape and reel specifications are in accordance with the second edition of *"IEC 60286-3"*. Basic dimensions are given in Figs 7 and 8, and Table 1.

#### Blister tape



#### Table 1 Dimensions of blister tape; see Fig.7

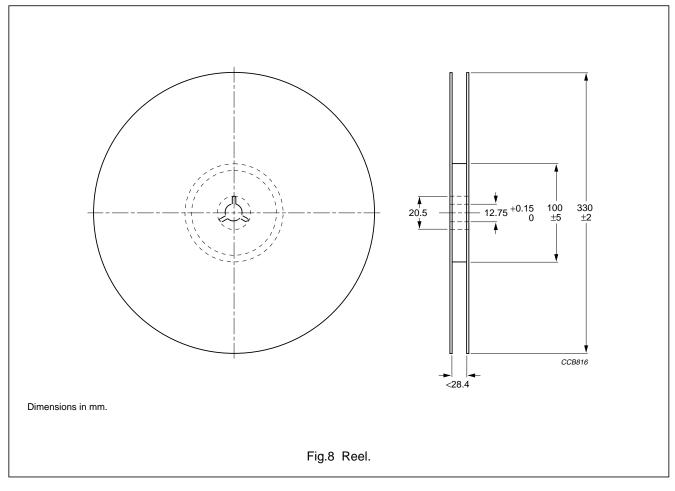
SYMBOL	DIMENSIONS	TOL.	UNIT
A <sub>0</sub>	10.6	±0.1	mm
B <sub>0</sub>	14.75	±0.1	mm
K <sub>0</sub>	4.75	±0.1	mm
W	24	±0.3	mm
D <sub>0</sub>	1.5	±0.1	mm
D <sub>1</sub>	1.5	±0.25	mm
P <sub>0</sub> ; note 1	4	±0.1	mm
P <sub>1</sub>	12	±0.1	mm
P <sub>2</sub>	6	±0.1	mm
Т	0.3	±0.1	mm

#### Note

1.  $P_0$  pitch tolerance over any 10 pitches is  $\pm 0.2$  mm.

## IIC10P-14/4 IIC10-14/4

#### **Reel specifications**



#### **Packaging quantities**

IICs are delivered taped and reeled in quantities of 1000 units.

#### Storage requirements

These storage requirements should be observed in order to ensure the soldering of the exposed electrode:

- Maximum ambient temperature shall not exceed 40 °C. Storage temperature higher than 40 °C could result in the deformation of packaging materials.
- Maximum relative humidity recommended for storage is 70% RH. High humidity with high temperature can accelerate the oxidation of the tin-lead plating on the termination and reduce the solderability of the components.
- Products shall not be stored in environments with the presence of harmful gases containing sulfur or chlorine.